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## N-Channel SuperFET<sup>®</sup> II MOSFET

### 800 V, 2.2 A, 4.3 $\Omega$

#### Features

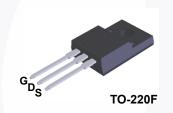
- R<sub>DS(on)</sub> = 3.4 Ω (Typ.)
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 6.8 nC)
- Low E<sub>oss</sub> (Typ. 0.8 uJ @ 400V)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 36 pF)
- 100% Avalanche Tested
- RoHS Compliant
- · ESD Improved Capability

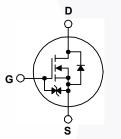
#### Applications

- AC DC Power Supply
- LED Lighting

## Description

SuperFET<sup>®</sup> II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as Audio, Laptop adapter, Lighting, ATX power and industrial power applications.





#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		FCPF4300N80Z	Unit				
V <sub>DSS</sub>	Drain to Source Voltage		800	V			
V <sub>GSS</sub>	Cata ta Sauraa Maltaga	- DC	. 7	±20	- V		
	Gate to Source Voltage	- AC (f >	1 Hz)	±30			
1	Drain Current	- Continuous (T <sub>C</sub> = 25 <sup>o</sup> C)		2.2*	A		
I <sub>D</sub>		- Continuous (T <sub>C</sub> = 100 <sup>o</sup> C)		1.4*	A		
I <sub>DM</sub>	Drain Current	- Pulsed (I	(Note 1)		Α		
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)			8.2	mJ		
I <sub>AR</sub>	Avalanche Current (Note 1)			0.32	Α		
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)			0.19	mJ		
dv/dt	MOSFET dv/dt		100	V/ns			
	Peak Diode Recovery dv/dt	Note 3)	20				
P <sub>D</sub>	Bower Dissipation	(T <sub>C</sub> = 25°C)		19.2	W		
	Power Dissipation	- Derate Above 25°C		0.15	W/ºC		
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	°C		
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300	°C		
Drain current limited	d by maximum junction temperature, with h	eatsink.			·		

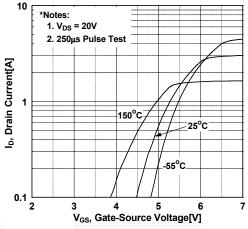
#### Thermal Characteristics

Symbol	Parameter	FCPF4300N80Z	Unit		
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	6.5	°C/W		
$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	0/10		

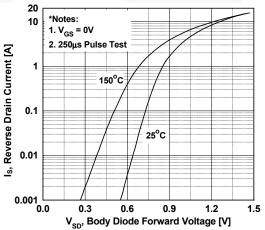
Part NumberTop MarkFCPF4300N80ZFCPF4300N80Z		Top Mark	Pac	ckage Packing Method Reel Siz		ize	Tape Wid	ith C	Quantity	
		TO-2	O-220F Tube N/A			N/A		50 units		
Electrica	l Chara	icteristics T <sub>C</sub> = 25	5 <sup>o</sup> C unle	ess oth	erwise noted.					
Symbol		Parameter		Test Conditions			Min.	Тур.	Max.	Unit
Off Chara	cteristics									
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage		aae	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 25°C			800	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdov	Breakdown Voltage Temperature Coefficient		$I_D = 1 \text{ mA}, \text{ Referenced to } 25^{\circ}\text{C}$			-	0.85	-	V/ºC
	Zero Gate Voltage Drain Current			$V_{DS}$ = 800 V, $V_{GS}$ = 0 V $V_{DS}$ = 640 V, $V_{GS}$ = 0 V, $T_C$ = 125°C			-	-	25	
IDSS							-	-	250	μA
I <sub>GSS</sub>	Gate to B	Gate to Body Leakage Current			±20 V, V <sub>DS</sub> = 0 V		-	-	±10	μA
On Charao	cteristics									
V <sub>GS(th)</sub>	Gate Thre	eshold Voltage		V <sub>GS</sub> =	V <sub>DS</sub> , I <sub>D</sub> = 0.16 mA		2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Dra	ain to Source On Resista	ance	V <sub>GS</sub> =	10 V, I <sub>D</sub> = 0.8 A		-	3.4	4.3	Ω
9 <sub>FS</sub>	Forward <sup>•</sup>	Transconductance		$V_{DS}$ =	20 V, I <sub>D</sub> = 0.8 A		-	0.52	-	S
Dynamic (	Character	ristics								
C <sub>iss</sub> Input Capacitance						267	355	pF		
C <sub>oss</sub>		apacitance		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, f = 1 MHz			12	16	pF	
C <sub>rss</sub>	-	Transfer Capacitance				-	0.78	-	pF	
C <sub>oss</sub>		out Capacitance		V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, f = 1 MHz			-	6.2	-	pF
C <sub>oss(eff.)</sub>	Effective	ffective Output Capacitance		$V_{DS} = 0 V \text{ to } 480 V, V_{GS} = 0 V$			-	36	-	pF
Q <sub>g(tot)</sub>	Total Gate	e Charge at 10V			640 V, I <sub>D</sub> = 1.6 A,		-	6.8	8.8	nC
Q <sub>gs</sub>	Gate to S	ource Gate Charge		$V_{GS} = 10 V$		-	1.38	-	nC	
Q <sub>gd</sub>	Gate to D	rain "Miller" Charge				(Note 4)	-	3.0	-	nC
ESR	Equivaler	nt Series Resistance		f = 1 N	1Hz		-	2.9	-	Ω
Switching	Charact	eristics								
t <sub>d(on)</sub>		Delay Time					-	10	30	ns
t <sub>r</sub>		Rise Time		V <sub>DD</sub> =	400 V, I <sub>D</sub> = 1.6 A,	-	-	6.5	23	ns
t <sub>d(off)</sub>		Delay Time		$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 4.7 \Omega$ (Note 4)			21	52	ns	
t <sub>f</sub>	Turn-Off	,					16	42	ns	
	ree Died	e Characteristics				, ,	/			
I <sub>S</sub>		Continuous Drain to So	ource D	)iode Fr				-	2.2	A
I <sub>SM</sub>		Pulsed Drain to Source					-	-	3.2	A
V <sub>SD</sub>		Source Diode Forward V			= 0 V, I <sub>SD</sub> = 1.6 A		-	-	1.2	V
t <sub>rr</sub>		Recovery Time	onago	$V_{GS} = 0 V, I_{SD} = 1.6 A,$ $V_{IF}/dt = 100 A/\mu s$		-	209	-	ns	
Q <sub>rr</sub>		Recovery Charge				-	1.2	-	μC	
lotes:		,			·					
	g: pulse width lir	mited by maximum junction tem	perature.							
2. I <sub>AS</sub> = 0.32 A, R										

#### **Typical Performance Characteristics Figure 1. On-Region Characteristics** V<sub>GS</sub> = 10.0V 8.0V 7.0V 6.5V 6.0V l<sub>b</sub>, Drain Current[A] 5.5V 5.0V Notes: 1. 250µs Pulse Test 2. $T_{C} = 25^{\circ}C$ 0.1 ∟ 0.3 1 10 20 V<sub>DS</sub>, Drain-Source Voltage[V] Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage** 8 \*Note: T<sub>C</sub> = 25°C Drain-Source On-Resistance R<sub>DS(ON)</sub> [Ω], $V_{GS} = 10V$ V<sub>GS</sub> = 20V 2 0 1 2 3 4 I<sub>D</sub>, Drain Current [A] **Figure 5. Capacitance Characteristics** 10000 1000 Ciss Capacitances [pF] 100 Coss 10 \*Note: 1. V<sub>GS</sub> = 0V 2. f = 1MHz Crss 1 Ciss = Cgs + Cgd (Cds = shorted) Coss = Cds + Cgd Crss = Cgd 0.1 └─ 0.1 1000 10 100 1 V<sub>DS</sub>, Drain-Source Voltage [V] ©2014 Fairchild Semiconductor Corporation 3 FCPF4300N80Z Rev. 1.1

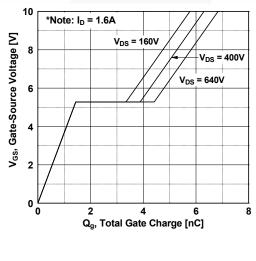
#### **Figure 2. Transfer Characteristics**

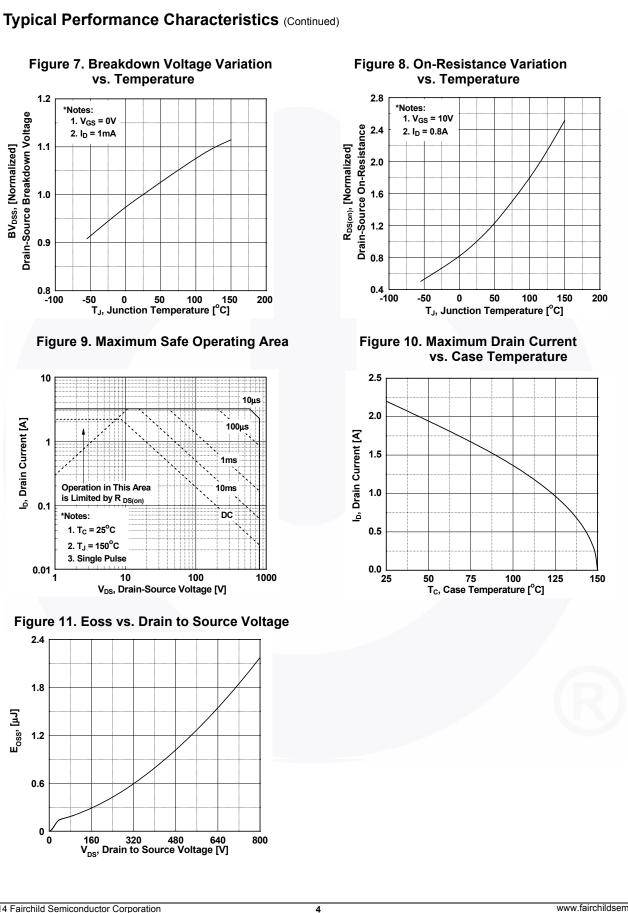






#### **Figure 6. Gate Charge Characteristics**

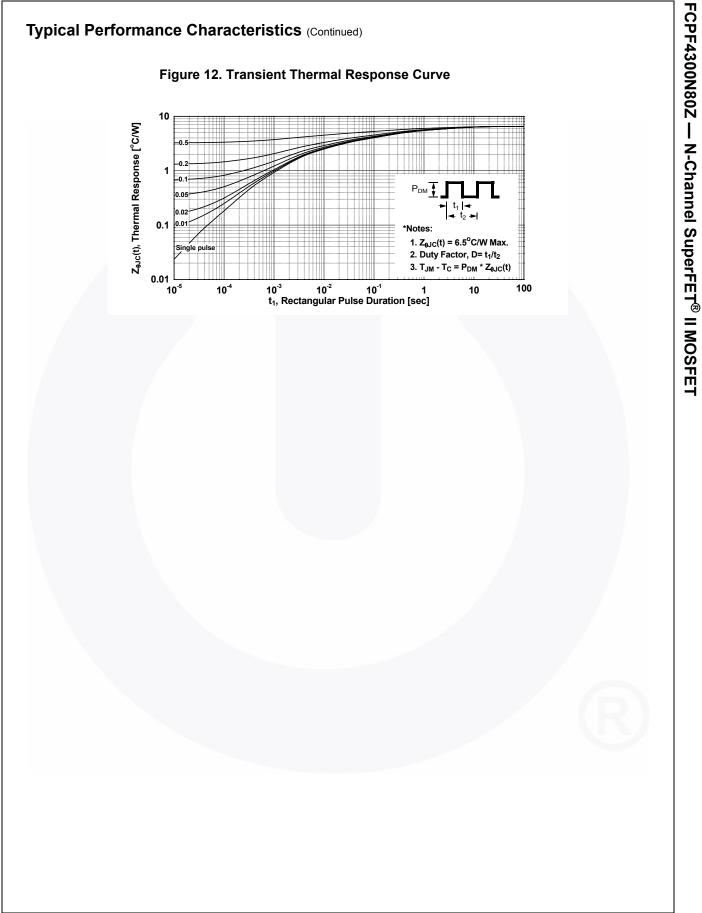


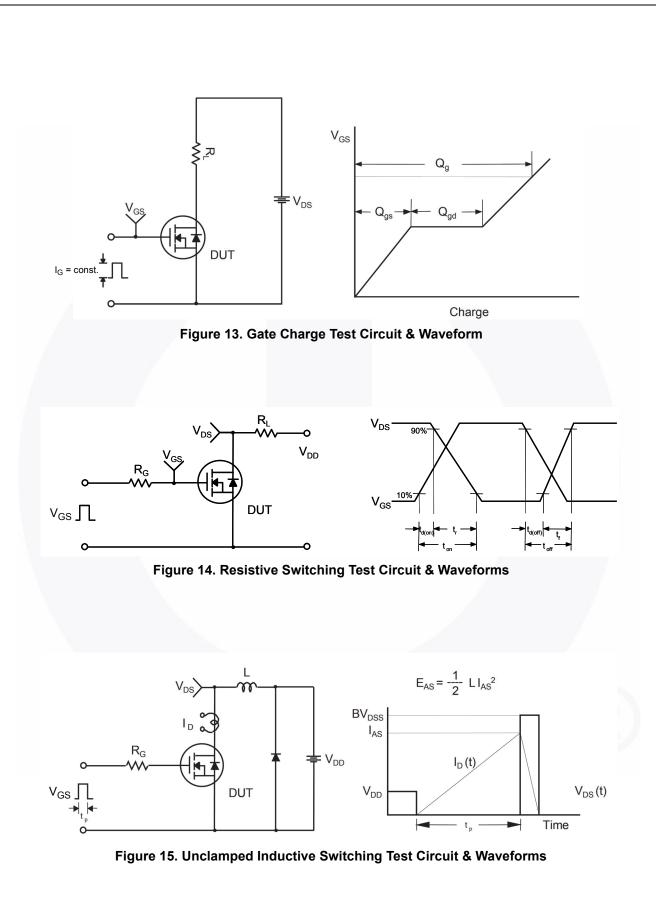


E<sub>oss</sub>, [μJ]

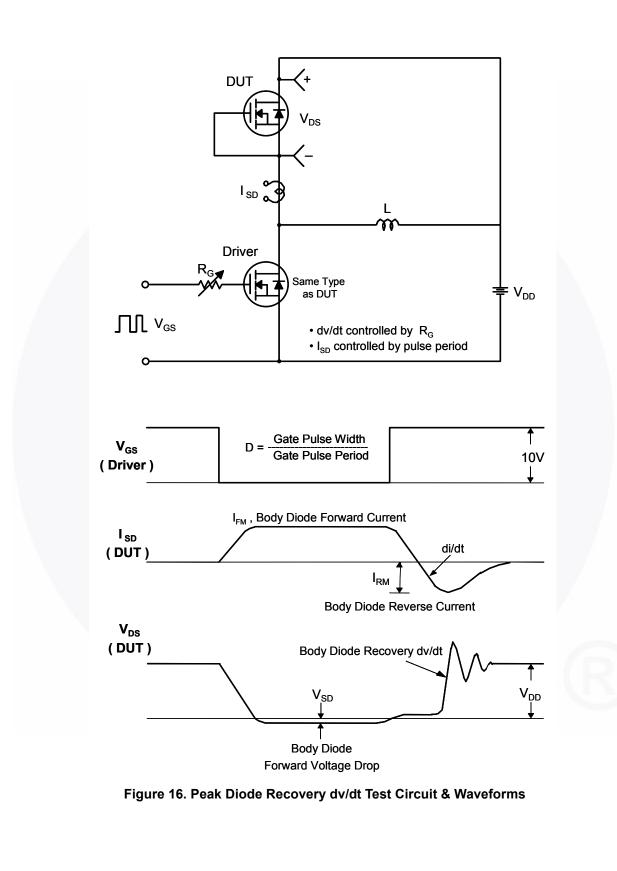
BV<sub>DSS</sub>, [Normalized]

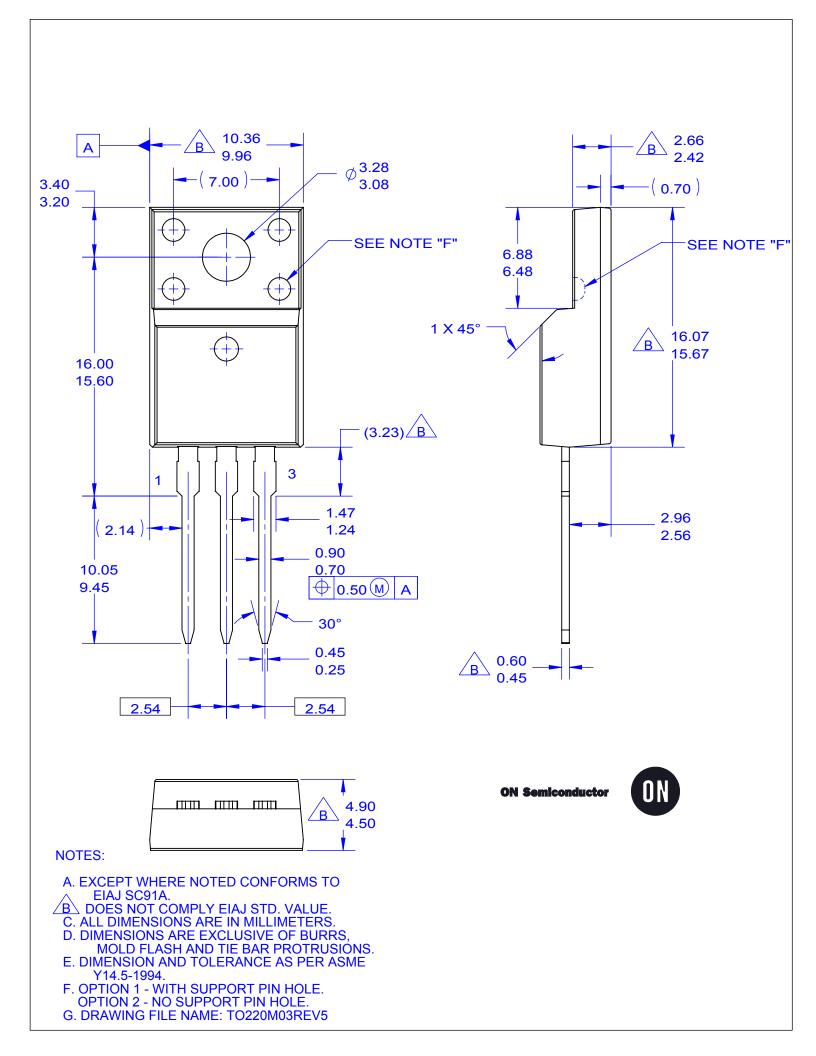
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